

**IN THE CLAIMS**

Please cancel claims 4, 14, 16, 17, 19 and 20 without prejudice or disclaimer as to their subject matter and amend claims 1, 5, 10-13, 15, 18 and 21 as follows:

1. (Currently Amended) A plasma display device, comprising:

a plasma display panel comprising a front surface that displays images and a back surface opposite to the front surface;

a chassis base attached to the back surface of the plasma display panel to support the plasma display panel, the chassis base comprising a plurality of driving circuit boards mounted on the chassis base;

a front cabinet arranged adjacent to the front surface of the plasma display panel;

a back cover arranged adjacent to a surface of the chassis base opposite the surface of the chassis base adjacent to the plasma display panel, the back cover being integrally assembled to the front cabinet with the chassis base and the plasma display panel arranged in between the back cover and the front cabinet, the back cover having an interior surface that faces the chassis base and an exterior surface that faces away from the chassis base; and

a plurality of thermoelectric semiconductor devices arranged on one of the interior surface and the exterior surface of the back cover, each of said plurality of thermoelectric semiconductor devices comprising a heat absorbing surface that faces the chassis base and a heat emitting surface that faces an exterior side of the back cover, the plurality of thermoelectric semiconductor devices being adapted to discharge heat generated by the

18 plasma display panel and the plurality of driving circuit boards to the exterior side of the  
19 back cover.

1 2. (Original) The plasma display device of claim 1, wherein each of the plurality of  
2 thermoelectric semiconductor devices are electrically connected to a power supply board via  
3 thermoelectric semiconductor drivers.

1 3. (Original) The plasma display device of claim 2, further comprising:  
2 a temperature sensor adapted to detect an internal temperature of the plasma display  
3 device and adapted to output corresponding signals; and  
4 a controller adapted to receive the corresponding temperature signals from the  
5 temperature sensor, the controller being programmed and configured to control an operation  
6 of the plurality of thermoelectric semiconductor devices based on the detected internal  
7 temperature of the plasma display device.

1 Claim 4. (Canceled)

1 5. (Currently Amended) The plasma display device of claim 1, wherein the plurality  
2 of thermoelectric semiconductor devices are arranged on [[a]] the interior surface of the back  
3 cover ~~adjacent to the chassis base~~ such that the heat emitting surfaces of the thermoelectric  
4 semiconductor devices contact the back cover.

1           6. (Original) The plasma display device of claim 1, wherein the plurality of  
2 thermoelectric semiconductor devices are fixed to the exterior surface of the back cover such  
3 that the heat absorbing surfaces of the thermoelectric semiconductor devices contact the back  
4 cover.

1           7. (Original) The plasma display device of claim 1, further comprising a plurality of  
2 thin metal plates, each thin metal plate being attached to respective heat absorbing surfaces  
3 of each of the plurality of thermoelectric semiconductor devices, each thin metal plate having  
4 a larger surface area than the corresponding thermoelectric semiconductor devices.

1           8. (Original) The plasma display device of claim 7, wherein the thin metal plates  
2 comprise a material selected from the group consisting of aluminum and copper.

1           9. (Original) The plasma display device of claim 7, further comprising a thermal  
2 conduction member arranged between each pair of the heat absorbing surfaces of the  
3 thermoelectric semiconductor devices and their corresponding thin metal plates.

1           10. (Currently Amended) The plasma display device of claim 1, further comprising  
2 a heat ~~sinks~~ sink being arranged on corresponding heat absorbing surfaces of the  
3 thermoelectric semiconductor devices.

11. (Currently Amended) The plasma display device of claim 10, further comprising  
a thermal conduction member arranged between ~~[[each]]~~ the heat sink and each  
corresponding heat absorbing surface of a corresponding thermoelectric semiconductor  
device.

12. (Currently Amended) A plasma display device, comprising:  
a plasma display panel comprising a front surface that displays images and a back  
surface opposite to the front surface;

a chassis base attached to the back surface of the plasma display panel to support the  
plasma display panel, the chassis base comprising a plurality of driving circuit boards  
mounted on the chassis base;

a front cabinet arranged adjacent to the front surface of the plasma display panel;  
a back cover arranged adjacent to a surface of the chassis base opposite the surface  
of the chassis base adjacent to the plasma display panel, the back cover being integrally  
assembled to the front cabinet with the chassis base and the plasma display panel arranged  
in between the back cover and the front cabinet;

a plurality of thermoelectric semiconductor devices arranged on the back cover, each  
of said plurality of thermoelectric semiconductor devices comprising a heat absorbing  
surface that faces the chassis base and a heat emitting surface that faces an exterior side of  
the back cover, the plurality of thermoelectric semiconductor devices being adapted to

16 discharge heat generated by the plasma display panel and the plurality of driving circuit  
17 boards to the exterior side of the back cover; and ~~The plasma display device of claim 1,~~  
18 ~~further comprising~~ a heat sink arranged on each heat emitting surface of a corresponding  
19 thermoelectric semiconductor device.

1 13. (Currently Amended) A plasma display device, comprising:  
2 a plasma display panel comprising a front surface that displays images and a back  
3 surface opposite to the front surface;  
4 a chassis base attached to the back surface of the plasma display panel to support the  
5 plasma display panel, the chassis base comprising a plurality of driving circuit boards  
6 mounted on the chassis base;  
7 a front cabinet arranged adjacent to the front surface of the plasma display panel;  
8 a back cover arranged adjacent to a surface of the chassis base opposite the surface  
9 of the chassis base adjacent to the plasma display panel, the back cover being integrally  
10 assembled to the front cabinet with the chassis base and the plasma display panel arranged  
11 in between the back cover and the front cabinet;  
12 a plurality of thermoelectric semiconductor devices arranged on the back cover, each  
13 of said plurality of thermoelectric semiconductor devices comprising a heat absorbing  
14 surface that faces the chassis base and a heat emitting surface that faces an exterior side of  
15 the back cover, the plurality of thermoelectric semiconductor devices being adapted to  
16 discharge heat generated by the plasma display panel and the plurality of driving circuit

boards to the exterior side of the back cover; and ~~The plasma display device of claim 1,~~  
~~further comprising~~ an insulating cover arranged over each heat emitting surface of  
corresponding thermoelectric semiconductor devices.

Claim 14 (Canceled)

15. (Currently Amended) The plasma display device of claim [[14]] 1, further  
comprising:  
a temperature sensor adapted to detect an internal temperature of the plasma display  
device and outputting corresponding temperature signals; and  
a controller arranged to receive the temperature signals from the temperature sensor,  
the controller being programmed and configured to control the thermoelectric semiconductor  
devices based on the received temperature signals.

Claims 16 and 17 (Canceled)

18. (Currently Amended) A plasma display device, comprising:  
a plasma display panel displaying images on a front surface, the plasma display panel  
having a back surface opposite to the front surface; and  
a back cover that covers and faces the back surface of the plasma display panel, the  
back cover being perforated by a plurality of openings, each opening comprising a

thermoelectric semiconductor device arranged therein and adapted to draw heat away from the plasma display panel and through the openings in the back cover to an exterior of the plasma display device, each thermoelectric semiconductor device comprising:

a p-type semiconductor material;

an n-type semiconductor material; and

metal strips, the p-type semiconductive material, the n-type semiconductor material and the metal strips each being electrically connected to each other inside an opening in said back cover.

Claims 19 and 20. (Canceled)

21. (Currently Amended) The plasma display device of [[19]] 18, further comprising a plurality of driving circuit boards arranged between said back cover and said back surface of said plasma display panel, said thermoelectric semiconductor devices also being adapted to draw heat away from the driving circuit boards and through the openings in the back cover to an exterior of the plasma display device.

22. (Original) The plasma display device of claim 21, further comprising a heat sink disposed between the back cover and the driving circuit boards.

23. (Original) The plasma display device of claim 22, the heat sink being in direct

contact with circuit elements on said driving circuit boards.

24. (Original) The plasma display device of claim 22, said heat sink being separated by a predetermined distance from circuit elements on said driving circuit boards, said heat sink not being in contact with any circuit elements on said driving circuit boards.

25. (Original) The plasma display of claim 23, further comprising a thermal conduction member arranged between the heat sink and the back cover, the thermal conduction member being in contact with both said heat sink and the back cover and with the thermoelectric semiconductor elements in the openings in the back cover.

26. (Original) The plasma display of claim 25, the thermal conduction member being comprised of a material selected from the group consisting of silicon and a thin carbon sheet.

27. (Original) A plasma display device, comprising:  
a plasma display panel comprising a front surface that displays images and a back surface opposite to the front surface;  
a chassis base attached to the back surface of the plasma display panel and arranged to support the plasma display panel, the chassis base comprising a plurality of driving circuit boards mounted on the chassis base;  
a front cabinet positioned adjacent to the front surface of the plasma display panel;



8 a back cover arranged on a side of the chassis base opposite the side of the chassis  
9 base facing the plasma display panel, the back cover being integrally assembled to the front  
10 cabinet with the chassis base and the plasma display panel arranged in between;

11 a plurality of thermoelectric semiconductor devices arranged between the back cover  
12 and the chassis base and adapted to draw heat away from the driving circuit boards and the  
13 plasma display panel to an outside of the plasma display panel through the back cover; and

14 a heat sink arranged between the plurality of thermoelectric semiconductor devices  
15 and the chassis base, the heat sink being in contact with heat dissipating circuit elements on  
16 the driving circuit boards on the chassis base, the heat sink also being in contact with the  
17 plurality of thermoelectric semiconductor devices.

1 28. (Original) The plasma display panel of claim 27, said plurality of thermoelectric  
2 semiconductor devices being in contact with the back cover.

1 29. (Original) The plasma display panel of claim 27, the plurality of thermoelectric  
2 semiconductor devices not being in contact with the back cover and being separated from the  
3 back cover by a predetermined distance.

1 30. (Original) The plasma display panel of claim 29, the back cover being perforated  
2 by a plurality of holes, said plurality of holes being adapted for ventilation and not for  
3 accommodation of thermoelectric semiconductor devices.